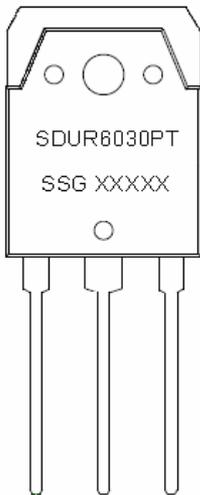




Technical Data
Data Sheet N1469, Rev. A

Green Products

Marking Diagram:



Where XXXXX is YYWWL

SDUR = Device Type
60 = Forward Current (60A)
30 = Reverse Voltage (300V)
PT = Configuration
SSG = SSG
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

Ordering Information:

Device	Package	Shipping
SDUR6030PT	TO-3P (Pb-Free)	30 pcs / tube

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Inverse Voltage	V_{RWM}	-	300	V
Average Forward Current	$I_{F(AV)}$	50% duty cycle @Tc=100°C, rectangular wave form	60	A
Peak One Cycle Non-Repetitive Surge Current (Per leg)	I_{FSM}	8.3ms, Half Sine pulse	400	A



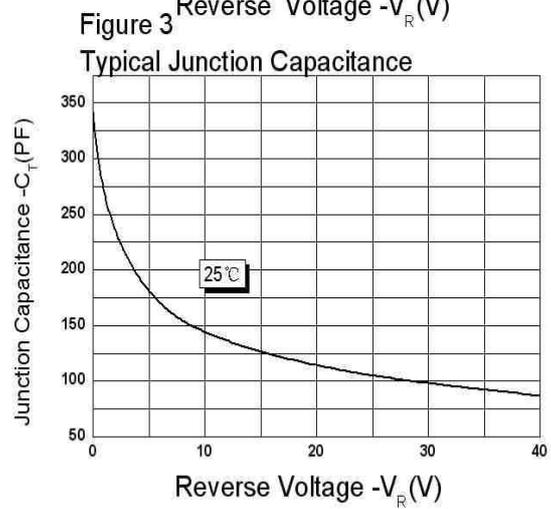
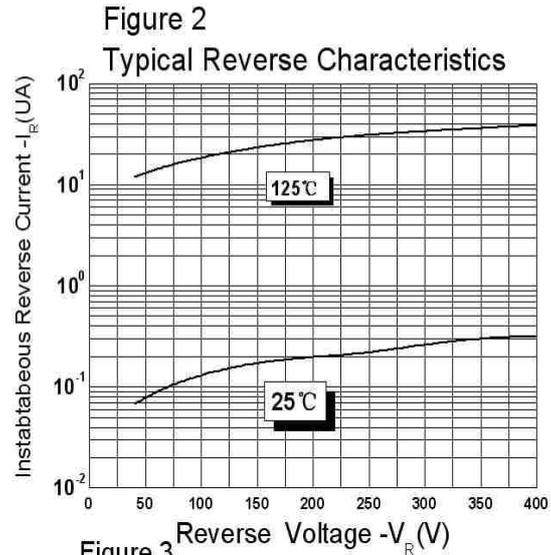
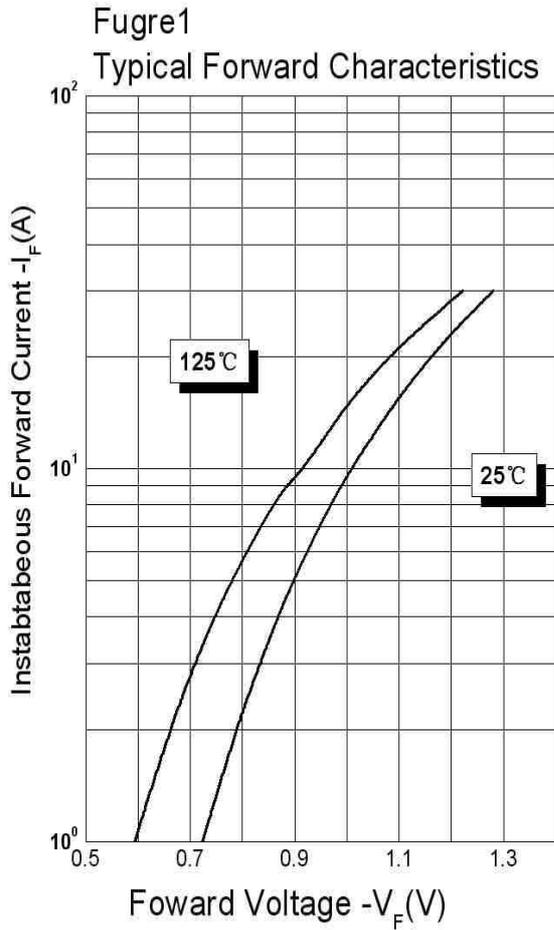
Electrical Characteristics:

Characteristics	Symbol	Condition	Max.	Units
Forward Voltage Drop(Per leg)*	V_{F1}	@ 30A, Pulse, $T_J = 25^\circ\text{C}$	1.3	V
	V_{F2}	@ 30A, Pulse, $T_J = 150^\circ\text{C}$	1.1	V
Reverse Current*	I_{R1}	@ $V_R = \text{rated } V_R$ $T_J = 25^\circ\text{C}$	5.0	μA
	I_{R2}	@ $V_R = \text{rated } V_R$ $T_J = 125^\circ\text{C}$	1.0	mA
Reverse Recovery Time	t_{rr1}	$I_F=500\text{mA}$, $I_R=1\text{A}$, and $I_{rm}=250\text{mA}$	45	ns

* Pulse width < 300 μs , duty cycle < 2%

Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	T_J	-	-55 to +150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-	-55 to +150	$^\circ\text{C}$
Maximum Thermal Resistance Junction to Case	$R_{\theta JC}$	DC operation	1.0	$^\circ\text{C/W}$
Approximate Weight	wt	-	6.7	g
Case Style	TO-3P			



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